

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

| | | | |
|-----------------------|--|---|-----------------------------|
| In re application of: | Joseph Kuczynski et al | : | Date: March 18, 2004 |
| Group Art Unit: | Unassigned | : | IBM Corporation |
| Examiner: | Unassigned | : | Intellectual Property Law |
| Serial No.: | Unassigned | : | Dept. 917, Bldg. 006-1 |
| Filed: | Herewith | : | 3605 Highway 52 North |
| Title: | LAND GRID ARRAY (LGA) INTERPOSER WITH ADHESIVE- RETAINED CONTACTS AND METHOD OF MANUFACTURE | : | Rochester, Minnesota 559501 |

INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. §1.97

Commissioner for Patents
PO Box 1450
Alexandria, VA 22313-1450

Sir:

Applicants request that the information listed on the attached Form PTO/SB/08A be considered by the Office during the pendency of the above entitled application, pursuant to 37 C.F.R. §1.97. In accordance with 37 C.F.R. §1.97(h), the filing of this Information Disclosure Statement shall not constitute an admission that any information cited therein is, or is considered to be, material to patentability as defined in 37 C.F.R. §1.56(b). In the interest of full and complete disclosure to the Office, some or all of the art cited herein may not be considered by Applicant(s) or the Undersigned to be material under the new standard of materiality defined in 37 C.F.R. §1.56(b), enacted March 16, 1992, but may be material under the old standard of materiality defined in 37 C.F.R. §1.56(a), last amended on November 28, 1988, or may merely be technical background which may be of interest to the Examiner. In accordance with 37 C.F.R. §1.97(g), the filing of this Information Disclosure Statement shall not be construed to mean that a search has been made.

Serial No. Unassigned
Docket No. ROC920040017US1

This Information Disclosure Statement is being filed under 37 C.F.R. §1.97(b)(1) within three months of the filing date of the present application. Accordingly no filing fee is required.

Date: March 18, 2004

IBM Corporation
Intellectual Property Law, Dept. 917
3605 Highway 52 North
Rochester, MN 55901

(507) 253-2555 voice
(507) 253-2382 fax

Respectfully submitted,

By



Leslie J. Payne, Attorney
Registration No. 26,378

PTO/SB/08A

**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**Sheet 1 of 2

Application Number.: Unassigned
 Filing Date: Herewith
 First Named Inventor: Kuczynski et al
 Art Unit: Unassigned
 Examiner Name: Unassigned
 Attorney Docket Number.: ROC920040017US1

U.S. PATENT DOCUMENTS

| Examiner Initials* | Cite No. ¹ | <u>Document Number</u> | Publication Date MM-DD-YYYY | Name of Patentee or Applicant of Cited Document | Pages, Columns or Lines Where Relevant Passages or Figs. Appear |
|-----------------------|--------------------------|---|--------------------------------|--|---|
| | | Number - Kind Code ² (if known) | | | |
| | AA | US - 6264476B1 | 07/24/2001 | Che-yu Li et al | |
| | AB | US - 6528984B2 | 03/04/2003 | Brian Samuel Beaman et al | |
| | | | | | |
| | | | | | |
| | | | | | |
| | | | | | |
| | | | | | |
| | | | | | |
| | | | | | |
| | | | | | |
| | | | | | |
| | | | | | |
| | | | | | |

FOREIGN PATENT DOCUMENTS

| Examiner Initials | Cite No. ¹ | <u>Foreign Patent Document</u> | Publication Date MM-DD- YYYY | Name of Patentee or Applicant of Cited Document | Pages, Columns or Lines Where Relevant Passages or Figs. Appear | T ⁶ |
|----------------------|--------------------------|--|---------------------------------------|---|--|----------------|
| | | Country ³ - Number ⁴ - Kind Code ⁵ Code (if known) | | | | |
| | AC | JP -11 - 31541 - A | 02/02/1999 | Kawabe | | X |
| | | | | | | |
| | | | | | | |
| | | | | | | |
| | | | | | | |

| | | | |
|--------------------|--|-----------------|--|
| Examiner Signature | | Date Considered | |
|--------------------|--|-----------------|--|

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹ Applicant's unique citation designation number (optional). ² See Kind Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3).

⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST.16 if possible. ⁶ Applicant is to place a check mark here if English language translation is attached.

PTO/SB/08A

**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

Sheet 2 of 2

Application Number.: Unassigned
 Filing Date: Herewith
 First Named Inventor: Kuczynski et al
 Art Unit: Unassigned
 Examiner Name: Unassigned
 Attorney Docket Number.: ROC920040017US1

OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS

| Examiner Initials | Cite No. ¹ | Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and or country where published. | T ² |
|-------------------|-----------------------|--|----------------|
| | AD | IBM Technical Disclosure Bulletin, Vol. 33, No. 5, October 1990, "Compressible-Contact Interconnection Scheme" by K. J. Puttlitz and H. Wenskus, pp. 394-395 | |
| | AE | US Patent Application Publication 2001/0001748A1, May 24, 2001, "Conduction Assist Member and Manufacturing Method of the Same" by Toshimasa Ochiai | |
| | AF | US Patent Application Publication 2001/0020546A1, September 13, 2001, "Electrical Contact Structures Formed by Configuring a Flexible Wire to Have a Springable Shape And Overcoating the Wire With at Least One Layer of a Resilient Conductive Material, Methods of Mounting the Contact Structures to Electronic Components, and Applications for Employing the Contact Structures" by Benjamin N. Eldridge et al | |
| | AG | US Patent Application Publication 2001/0024892A1, September 27, 2001, "Contact Sheet" by Toshimasa Ochiai | |
| | AH | US Patent Application Publication 2003/0146510A1, August 7, 2003, "Elastomer Interposer for Grid Array Packages and Method of Manufacturing the Same" by Ray Chien | |
| | AI | US Patent Application Publication 2003/0003784A1, January 2, 2003, "Interposer Assembly" by Douglas A. Neidich | |

| | | | |
|--------------------|--|-----------------|--|
| Examiner Signature | | Date Considered | |
|--------------------|--|-----------------|--|

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹ Applicant's unique citation designation number (optional).

² Applicant is to place a check mark here if English language translation is attached.